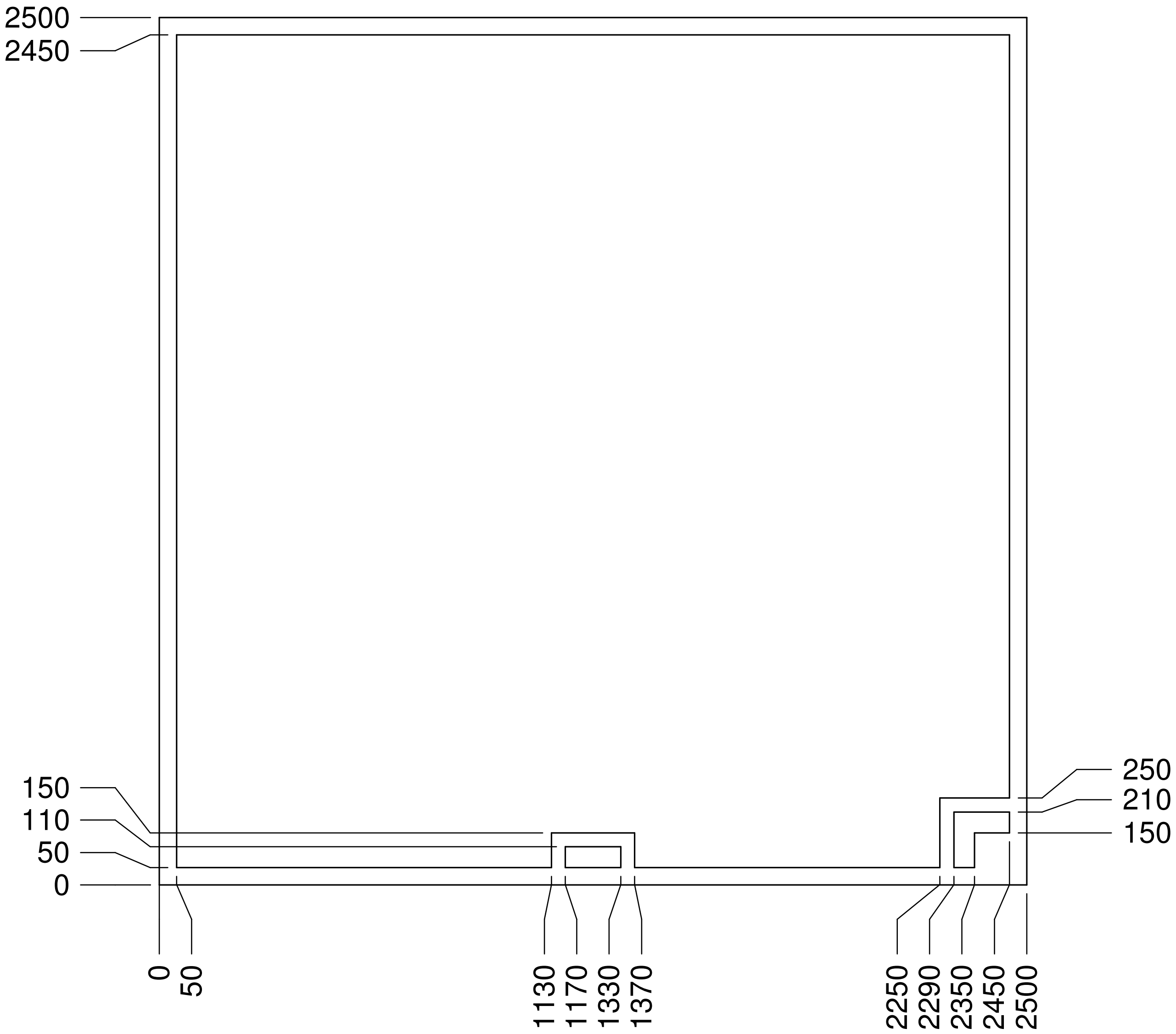
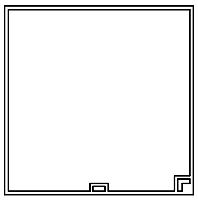
REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED





SCALE 10:1

Notes: (Unless Otherwise Specified).

1) DIE MATERIAL IS SILICON.
2) DIE THICKNESS IS 250 um (10 MIL).
3) METALLIZATION 1.0 um ALUMINUM (Al) OVER 0.75 um SiO_2.
4) DIE IS WITHOUT PASSIVATION.
5) WIRE BONDABLE WITH GOLD (Au) OR ALUMINUM (Al) WIRE.
6) DIFFERENTIAL PAIR (2 PADS) WITH LARGE GROUND PAD.
7) RF / MICROWAVE PARASITIC TEST APPLICATIONS.
8) TOLERANCE = ±1 um.

DIMENSIONS IN MICRONS
1000 um = 1. 0mm

PART NUMBER SYSTEM						
TD	-	2	-	2.5	-	DIF
SILICON TEST DIE		BOND PADS		DIE SIZE (mm)		DIFFERENTIAL PAIR

TOLERANCE UNLESS NOTED	
X.XX	+/- 0.01
X.XXX	+/- 0.005
X.XXXX	+/- 0.0005
ANGLES	+/- 0.5°

ALL DIMENSIONS IN
☒ INCHES ☐ MILLIMETERS

THIRD ANGLE PROJECTION

APPROVALS	DATE
DRAWN J. HINES	5/8/2010
ENG	
MFG	
QA	
CUST	
REVISED	

TopLine®

TITLE
Si TEST DIE
TD SERIES

SCALE	SIZE	DRAWING NO.	REV
50:1	A	152502	A

DO NOT SCALE DRAWING

SHEET 1 OF 1